Quad Flat No-Lead Plastic Package (QFN) Micro Lead Frame Plastic Package (MLFP)







FOR EVEN TERMINAL/SIDE

L64.9x9-S

64 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE

	MILLIMETERS			
SYMBOL	MIN	NOMINAL	MAX	NOTES
А	0.80	0.85	0.90	-
A1	-	-	0.05	-
A2	0.60	0.65	0.70	-
A3	0.25 REF			-
b	0.18	0.23	0.30	5, 8
D	9.00 BSC			-
D1	8.75 BSC			-
D2	3.70	3.80	3.90	7, 8
E	9.00 BSC			-
E1	8.75 BSC			-
E2	3.70	3.80	3.90	7, 8
е	0.50 BSC			-
L	0.30	0.40	0.50	8
L1	-	-	0.15	9
Ν	64			2
Nd	16			3
Ne	16			3
Р	-	-	0.50	-
θ	10	11	12	-
		•	•	Rev. 1 2/09

NOTES:

- 1. Dimensioning and tolerancing conform to ASME Y14.5-1994.
- 2. N is the number of terminals.
- 3. Nd and Ne refer to the number of terminals on each D and E.
- 4. All dimensions are in millimeters. Angles are in degrees.
- 5. Dimension b applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
- The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
- 7. Dimensions D2 and E2 are for the exposed pads which provide improved electrical and thermal performance.
- 8. Nominal dimensions are provided to assist with PCB Land Pattern Design efforts, see Intersil Technical Brief TB389.
- Depending on the method of lead termination at the edge of the package, a maximum 0.15mm pull back (L1) maybe present. L minus L1 to be equal to or greater than 0.3mm.

